

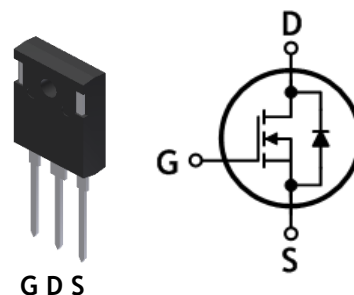
SWITCHING REGULATOR APPLICATION

Features

- 650V Super-junction MOSFET
- Low FOM $R_{DS(on)} * Q_g$
- Low drain-source On-resistance: $R_{DS(on)}=0.065\Omega$ (Max.)
- 100% avalanche tested
- RoHS compliant device

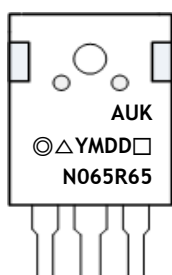
Ordering Information

Part Number	Marking	Package
SJMN065R65W	N065R65	TO-247



TO-247

Marking Information



Column 1: Manufacturer

Column 2: Production Information

e.g.) ◎△YMDD□

- ◎: Management code

- △: Machine Code

- YMDD: Date Code (Year, Month, Daily)

- □: Factory Management Code

Column 3: Device Code

Absolute maximum ratings ($T_c=25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Rating	Unit
Drain-source voltage	V_{DS}	650	V
Gate-source voltage	V_{GS}	± 30	V
Drain current (DC) (Note 1)	I_D	$T_c=25^\circ\text{C}$	51
		$T_c=100^\circ\text{C}$	32
Drain current (Pulsed) (Note 1)	I_{DM}	204	A
Single pulsed avalanche energy (Note 2)	E_{AS}	650	mJ
Repetitive avalanche current (Note 1)	I_{AR}	10	A
Repetitive avalanche energy (Note 1)	E_{AR}	43.1	mJ
Power dissipation	P_D	431	W
Diode dv/dt ruggedness (Note 3)	dv/dt	15	V/ns
MOSFET dv/dt ruggedness (Note 4)	dv/dt	50	V/ns
Junction temperature	T_J	150	$^\circ\text{C}$
Storage temperature range	T_{stg}	-55~150	$^\circ\text{C}$

Thermal Characteristics

Characteristic	Symbol	Rating	Unit
Thermal resistance, junction to case	$R_{th(j-c)}$	Max. 0.29	°C/W
Thermal resistance, junction to ambient	$R_{th(j-a)}$	Max. 50	

Electrical Characteristics ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	BV_{DSS}	$I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$	650	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$I_D=250\mu\text{A}$, $V_{DS}=V_{GS}$	2	-	4	V
Drain-source cut-off current	I_{DSS}	$V_{DS}=650\text{V}$, $V_{GS}=0\text{V}$	-	-	1	μA
	I_{GSS}	$V_{DS}=0\text{V}$, $V_{GS}=\pm 30\text{V}$	-	-	± 100	nA
Gate leakage current	$R_{DS(ON)}$	$V_{GS}=10\text{V}$, $I_D=19.4\text{A}$	-	0.055	0.065	Ω
Drain-source on-resistance	R_g	$f=1\text{MHz}$, Open drain	-	0.5	-	Ω
Internal gate resistance	C_{iss}	$V_{DS}=100\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	4510	-	pF
Input capacitance	C_{oss}		-	120	-	
Output capacitance	C_{rss}		-	5.4	-	
Reverse transfer capacitance	$t_{d(on)}$	$V_{DD}=300\text{V}$, $I_D=19.4\text{A}$, $R_G=10\Omega$, $V_{GS}=10\text{V}$	-	85	-	ns
Turn-on delay time (Note 5)	t_r		-	55	-	
Rise time (Note 5)	$t_{d(off)}$		-	210	-	
Turn-off delay time (Note 5)	t_f		-	15	-	
Fall time (Note 5)	Q_g	$V_{DS}=400\text{V}$, $V_{GS}=10\text{V}$, $I_D=38.8\text{A}$	-	94	-	nC
Total gate charge (Note 6)	Q_{gs}		-	22	-	
Gate-source charge (Note 6)	Q_{gd}		-	30	-	

Source-Drain Diode Ratings and Characteristics ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Source current (DC)	I_S	Integral reverse diode in the MOSFET	-	-	51	A
Source current (Pulsed)	I_{SM}		-	-	204	A
Forward voltage	V_{SD}	$V_{GS}=0\text{V}$, $I_S=51\text{A}$	-	-	1.7	V
Reverse recovery time (Note 5, 6)	t_{rr}	$I_S=19.4\text{A}$, $V_{GS}=0\text{V}$ $di_S/dt=50\text{A}/\mu\text{s}$	-	460	-	ns
Reverse recovery charge (Note 5, 6)	Q_{rr}		-	7.4	-	μC

Note:

1. Calculated continuous current based on maximum allowable junction temperature
2. $L=10\text{mH}$, $I_{AS}=10\text{A}$, $V_{DD}=150\text{V}$, Starting $T_J=25^{\circ}\text{C}$
3. $I_S \leq 9.7\text{A}$, $V_{DS} \leq 400\text{V}$, $di_S/dt \leq 100\text{A}/\mu\text{s}$, $T_J=25^{\circ}\text{C}$
4. $V_{DS} \leq 400\text{V}$, $I_S \leq 9.7\text{A}$
5. Guaranteed by design, not subject to production testing
6. Pulse test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$

Typical Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

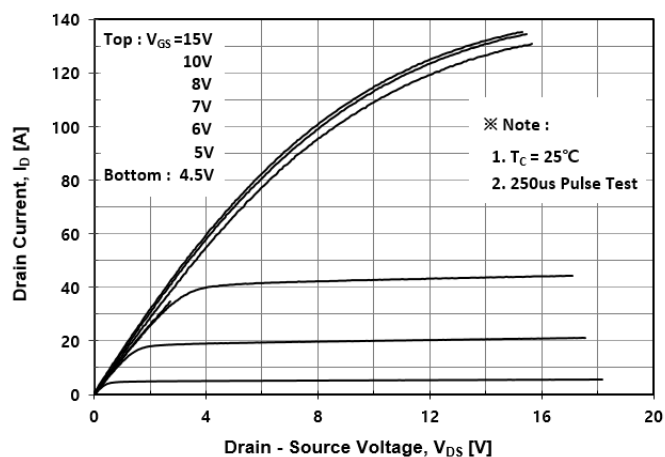


Fig. 2 Typical Transfer Characteristics

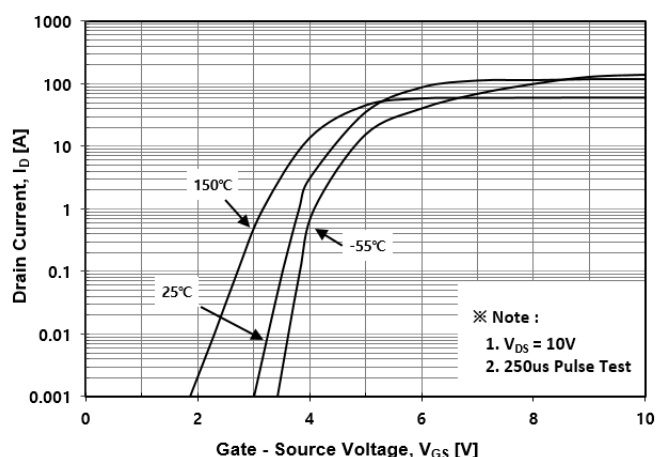


Fig.3 On-Resistance Variation with Drain Current and Gate Voltage

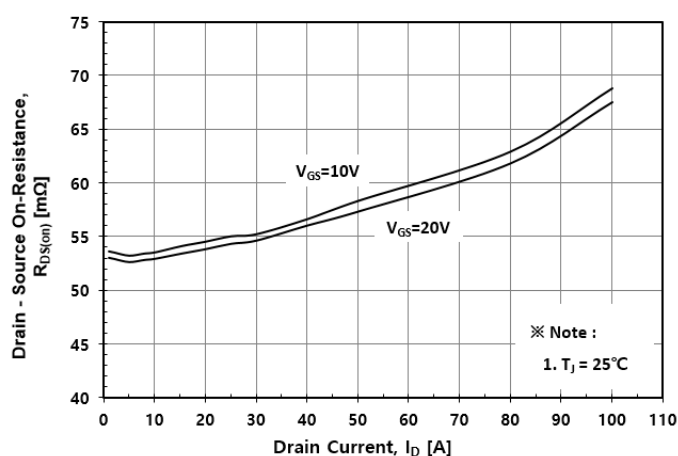


Fig. 4 Body Diode Forward Voltage Variation with Source Current

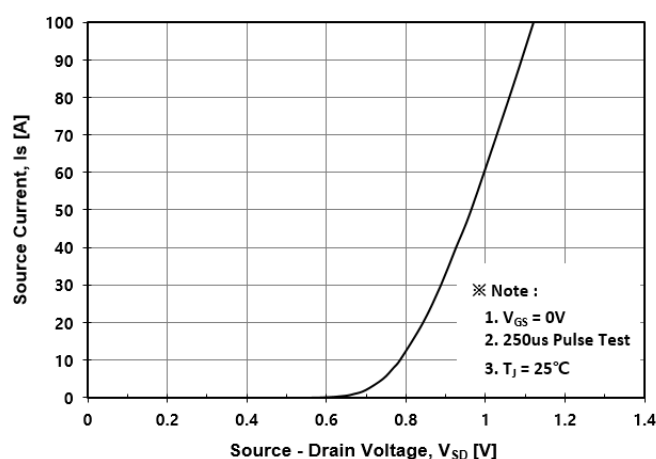


Fig. 5 Typical Capacitance Characteristics

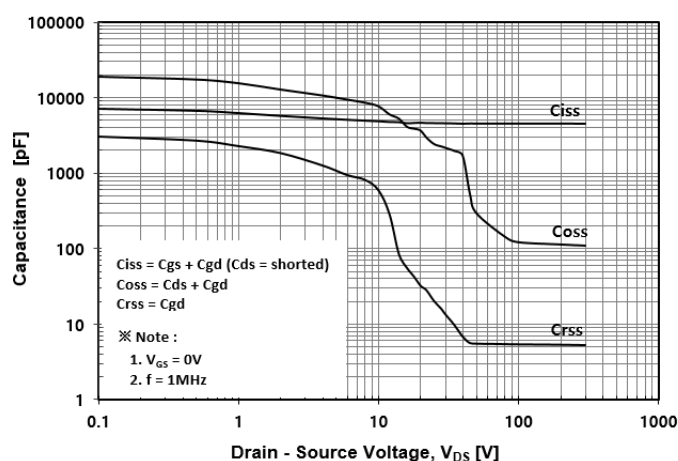
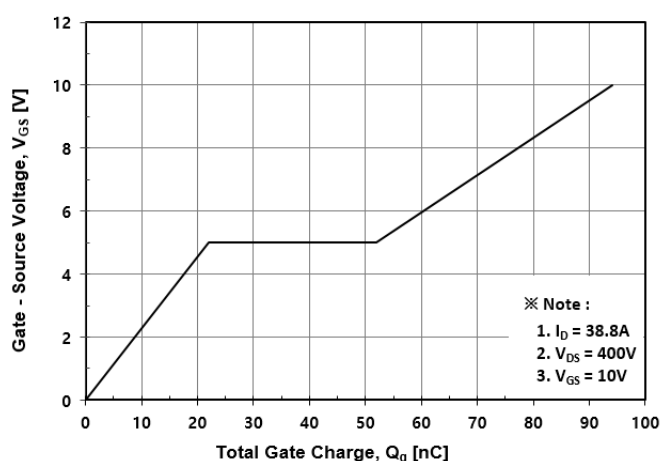


Fig. 6 Typical Total Gate Charge Characteristics



Drain - Source Breakdown Voltage
 BV_{DSS} , (Normalized)

※ Note :
 1. $V_{GS} = 0V$
 2. $I_{DS} = 250\mu A$

Junction Temperature, T_J [°C]

Junction Temperature, T_J [°C]	Normalized BV_{DSS}
-50	0.945
0	0.985
50	1.025
100	1.065
150	1.10

The graph shows the relationship between the drain-source on-resistance and the junction temperature for the 2N7000 MOSFET. The y-axis represents the normalized on-resistance, $R_{DS(ON)}$, ranging from 0 to 3. The x-axis represents the junction temperature, T_J , in degrees Celsius, ranging from -75 to 175. The curve starts at approximately 0.85 at -50°C and increases to about 2.4 at 150°C. A note specifies the test conditions: $V_{GS} = 10V$ and $I_D = 19.4A$.

Junction Temperature, T_J [°C]	Normalized $R_{DS(ON)}$
-50	0.85
0	0.95
25	1.00
50	1.20
75	1.50
100	1.80
125	2.10
150	2.40

※ Note :
 1. $V_{GS} = 10V$
 2. $I_D = 19.4A$

The graph shows the relationship between Drain Current (I_D) and Case Temperature (T_C) for the 2N3866 JFET. The y-axis represents Drain Current, I_D [A], ranging from 0 to 54. The x-axis represents Case Temperature, T_C [°C], ranging from 25 to 150. The curve starts at approximately 48 A at 25°C and decreases linearly to 0 A at 150°C.

Case Temperature, T_C [°C]	Drain Current, I_D [A]
25	48
50	42
75	36
100	30
125	24
150	0

Drain Current, I_D [A]

DC

Operation in This Area is Limited by $R_{DS(on)}$

※ Note :

1. $T_C = 25^\circ\text{C}$
2. $T_J = 150^\circ\text{C}$

10us

100us

1ms

10ms

100ms

Drain-Source Voltage, V_{DS} [V]

Transient thermal impedance, $Z_{\Theta JC}(t)$

Pulse Width, t [sec]

Single Pulse

$\delta = 0.01$
 $\delta = 0.02$
 $\delta = 0.05$
 $\delta = 0.1$
 $\delta = 0.2$
 $\delta = 0.5$

P_{DM}
 t_1
 t_2

※ Note :

1. $Z_{\Theta JC}(t) = 0.29^{\circ}\text{C/W}$ Max.
2. Duty Factor, $\delta = t_1 / t_2$
3. $T_{JM} - T_C = P_{DM} \times Z_{\Theta JC}(t)$

Fig. 12 Gate Charge Test Circuit & Waveform

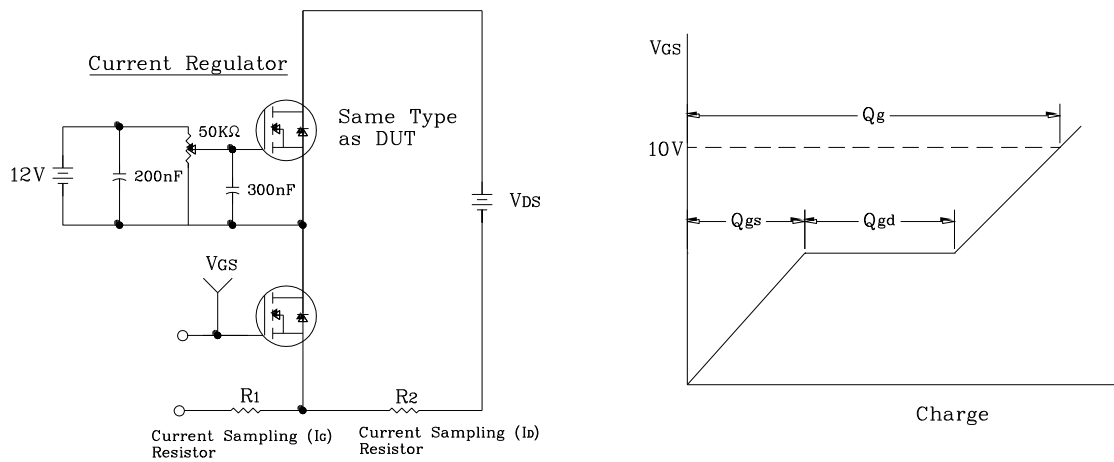


Fig. 13 Resistive Switching Test Circuit & Waveform

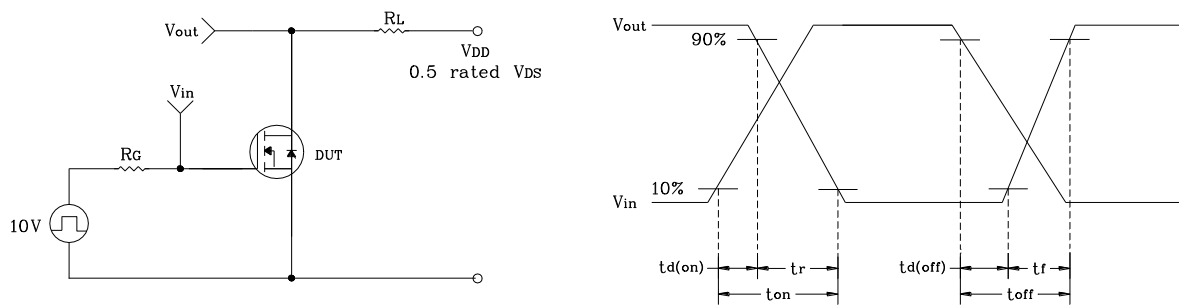


Fig. 14 E_{AS} Test Circuit & Waveform

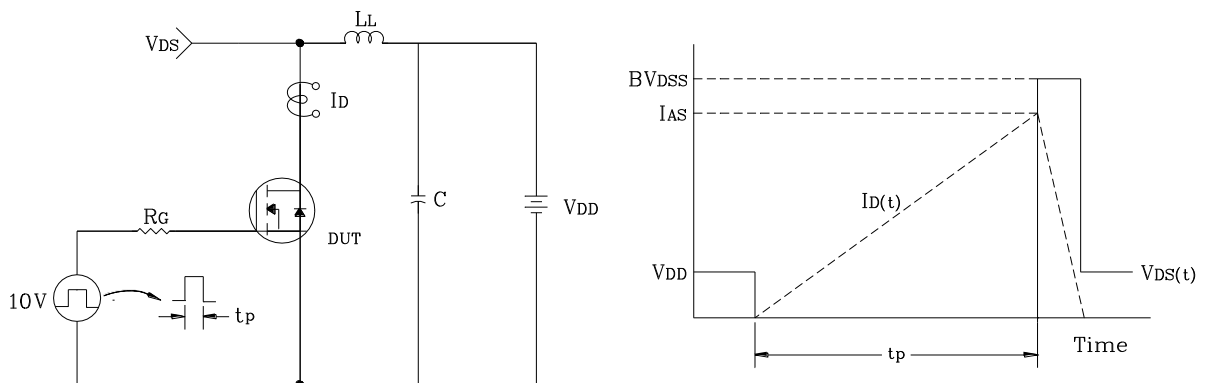
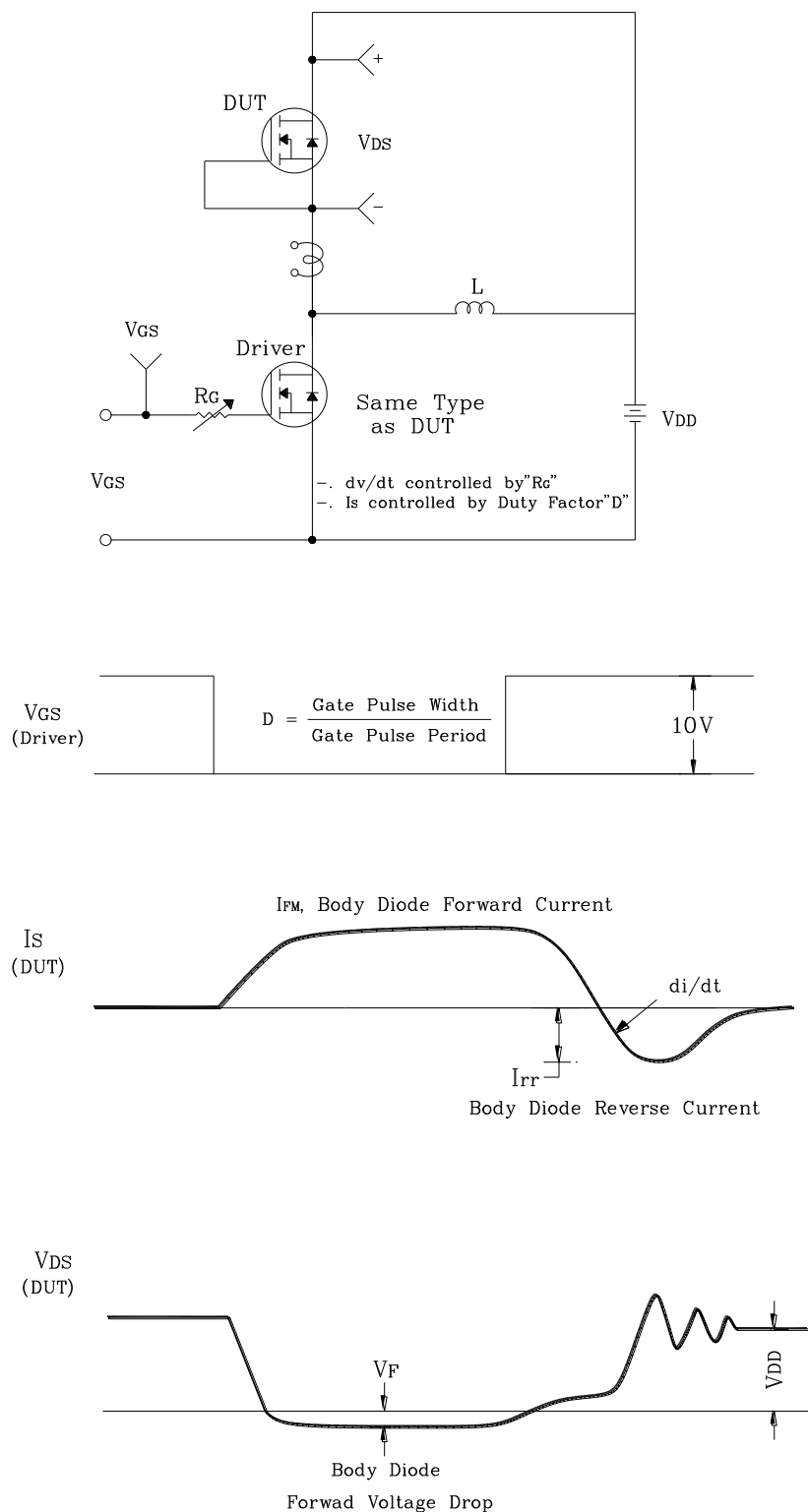
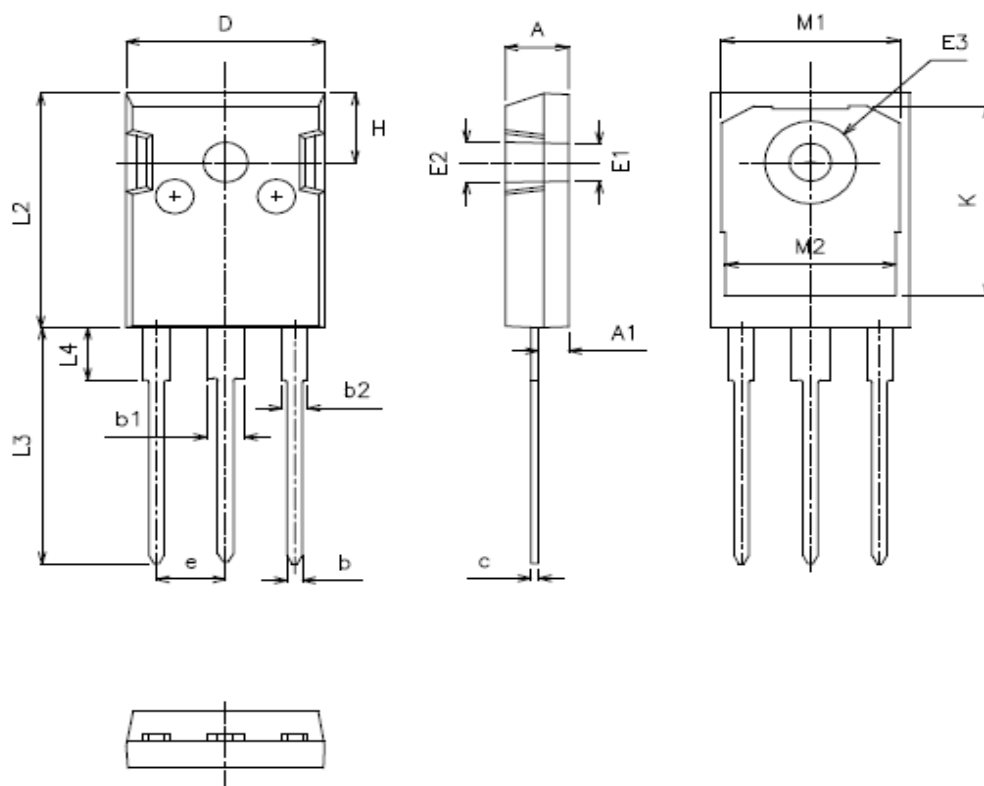


Fig. 15 Diode Reverse Recovery Time Test Circuit & Waveform



Package Outline Dimensions (Unit: mm)



SYMBOL	MILLIMETERS		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.26	2.41	2.56
b	1.10	1.20	1.30
b1	3.00	3.10	3.20
b2	2.00	2.10	2.20
c	0.50	0.60	0.70
D	15.60	15.80	16.00
E1	3.45	3.60	3.75
E2	3.55	3.70	3.85
E3	7.04	7.19	7.34
L2	20.80	21.00	21.20
L3	19.72	19.92	20.12
L4	3.95	4.10	4.25
e	5.29	5.44	5.59
H	6.00	6.15	6.30
K	16.25	16.45	16.65
M1	13.80	14.00	14.20
M2	13.10	13.30	13.50

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